

the wafer. In this way, the weight of the wafer is uniformly distributed between the three electrode pairs.

[0025] In this process, electrode pairs are applied to a flexible circuit board. Then, a mediation layer is applied to the electrodes. By way of example, indium is suitable for this mediation layer and may even have been applied to the electrodes in advance in a layer thickness of approx. 10 μm using an electrode deposition process. A layer of zinc is also able to improve the bonding of the various materials. The zirconium oxide layer is then applied to the indium layer. An insulating layer is applied to the other side of the electrode. Then, the layers are pressed together, so that they are joined to one another in a cold-welding operation. A rough surface of a zirconium oxide disk is of benefit to this operation.

[0039] In the present embodiment, the layer thicknesses and materials between the zirconium oxide layer and the insulating layer are as follows:

between 80 and 250 μm of zirconium oxide 6;
approx. 10 μm of indium and 5 μm of nickel as mediation layer
between zirconium oxide layer and copper electrode;
approx. 17.5 μm of electrode and supply layers made from copper 14, 15,
21;
approx. 25 μm for the circuit board made from Kapton or polyamide 10;
approx. 2.6 μm for the insulating layer of aluminum oxide 8; and
approx. 0.5 μm for the baseplate made from T 136 NiP 9.

Thank you for making these changes by Examiner's Amendment and for including these specifications in your continued examination of this application.

Wherefore further consideration and allowance of the claims is respectfully requested.

Respectfully submitted,



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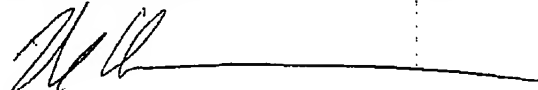
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CERTIFICATE OF SUBMISSION BY FACSIMILE TRANSMISSION

I hereby certify under 37 CFR §1.8 that this correspondence is being submitted to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 by facsimile transmission on March 19, 2006, fax numbers (571) 273 8300 and (571) 273 4569.



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